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10542040 - GAU: 1795

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<b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b> ( Not for submission under 37 CFR 1.99)	Application Number	10542040
	Filing Date	2006-02-06
	First Named Inventor	John Mize
	Art Unit	1795
	Examiner Name	Jason Berman
Attorney Docket Number		H0004870.70759 US -4015

U.S. PATENTS						
Examiner Initial*	Cite No	Patent Number	Kind Code <sup>1</sup>	Issue Date	Name of Patentee or Applicant of cited Document	Pages, Columns, Lines where Relevant Passages or Relevant Figures Appear
	1					

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U.S. PATENT APPLICATION PUBLICATIONS						
Examiner Initial*	Cite No	Publication Number	Kind Code <sup>1</sup>	Publication Date	Name of Patentee or Applicant of cited Document	Pages, Columns, Lines where Relevant Passages or Relevant Figures Appear
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20070134907

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**FOREIGN PATENT DOCUMENTS**

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Examiner Signature	/Jason Berman/	Date Considered	07/15/2009
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